

## / Descriptions

PDFN5*6 N
。
N-Channel MOSFET in a PDFN5*6 Plastic Package .

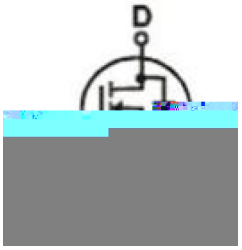
## / Features

Low $R_{DS(ON)}$ to minimize conductive loss ,low Gate Charge for fast switching ,Low Thermal resistance, HF Product.

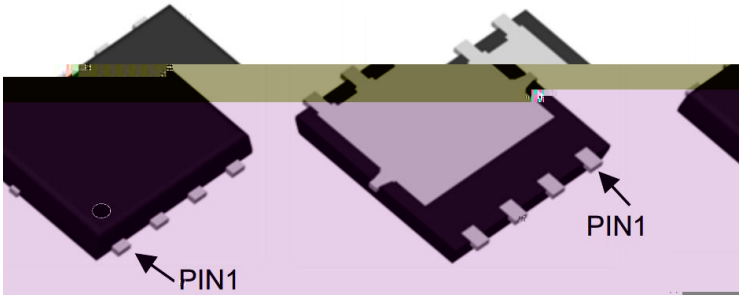
## / Applications

Battery Management

## / Equivalent Circuit




## / Pinning




PIN1、2、3： S PIN4：G PIN5、6、7、8：D

| Pin | 极性 |
|---|---|
| 1 | S |
| 2 | S |
| 3 | S |
| 4 | G |
| 5 | D |
| 6 | D |
| 7 | D |
| 8 | D |

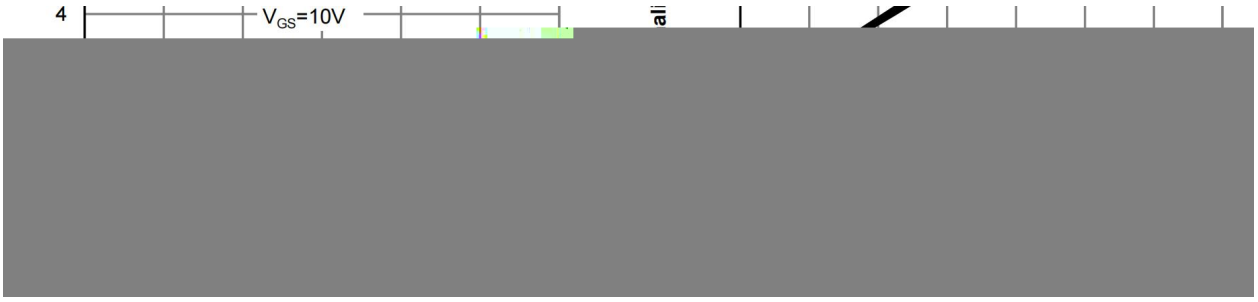
## / $h_{FE}$ Classifications & Marking

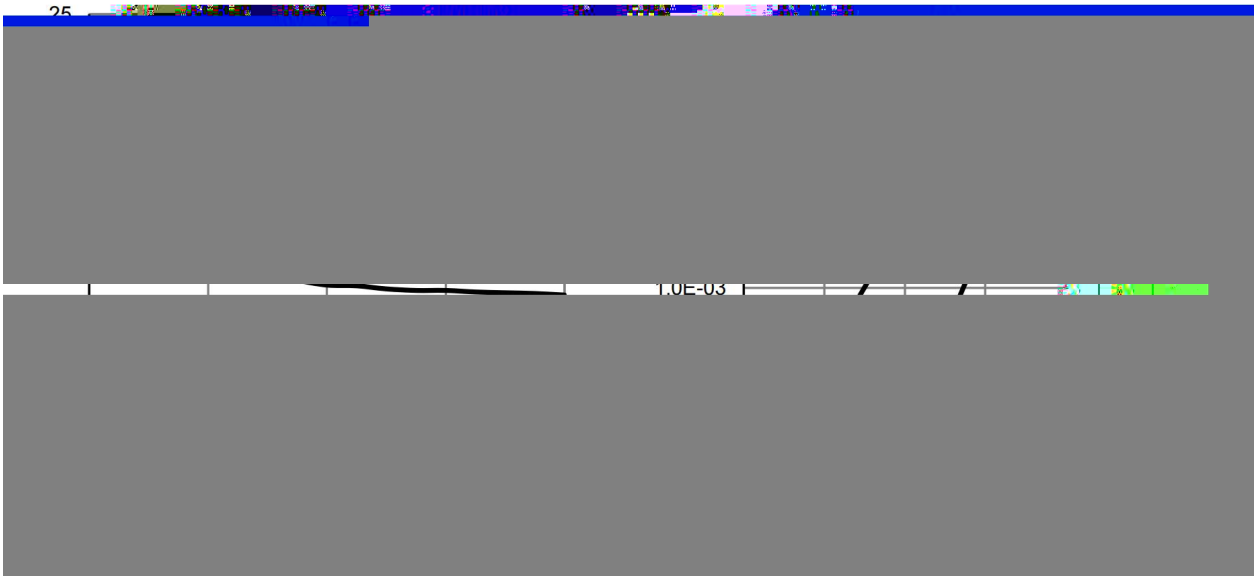
见印章说明。See Marking Instructions.

| Parameter | Symbol | Rating | Unit |
|---|---|---|---|
| Drain-Source Voltage | $V_{DS}$ | 30 | V |
| Drain Current - | | | |

## / Electrical Characteristic Curve



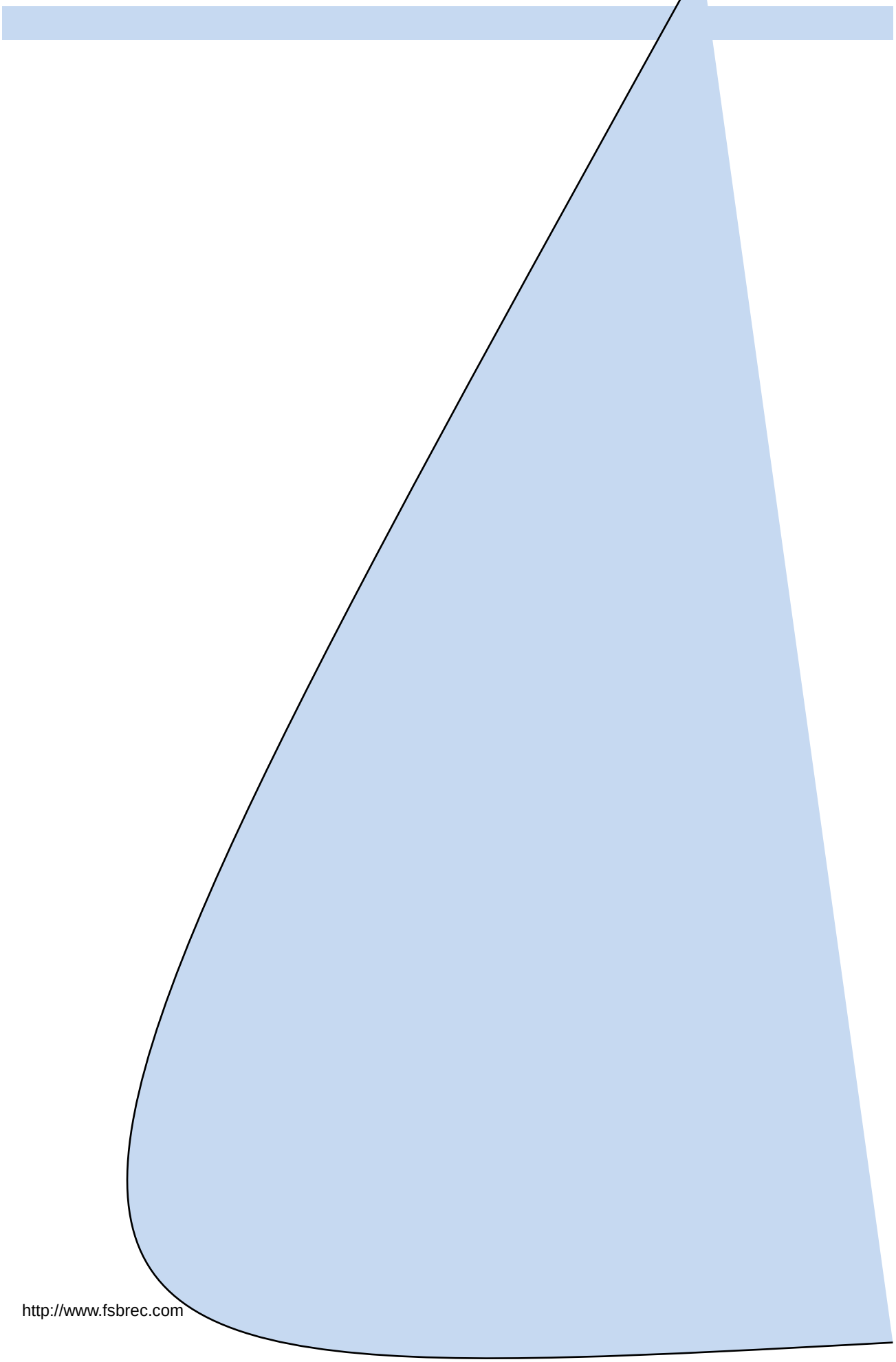


# BRCS080N03ZC

Rev.A May.-2021

**DATA SHEET**



BRBRBR

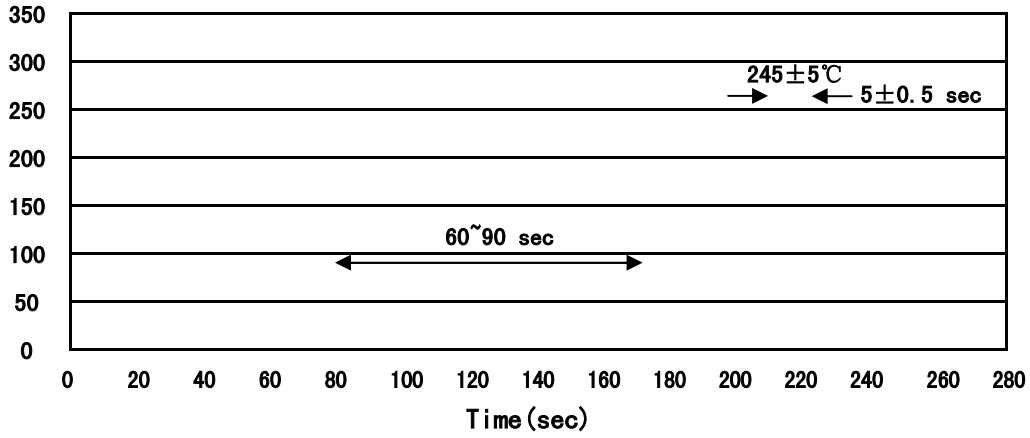
## / Marking Instructions

说明：

BR： 为公司代码

080N03

## ( ) / Temperature Profile for IR Reflow Soldering(Pb-Free)




| | | | |
|---|---|---|---|
| | | | Note: |
| 1 | 150 180 | 60 90sec; | 1.Preheating:150~180℃, Time:60~90sec. |
| 2 | 245±5 | 5±0.5sec; | 2.Peak Temp.:245±5℃, Duration:5±0.5sec. |
| 3 | 2 | 10℃/sec. | 3. Cooling Speed: 2~10℃/sec. |

## / Resistance to Soldering Heat Test Conditions

260±5℃ 10±1 sec. Temp.:260±5 Time:10±1 sec

## / Packaging SPEC.

/ REEL

| Package Type 封装形式 | Units | | | | | Dimension | | (unit mm³) |
|---|---|---|---|---|---|---|---|---|
| | Units/Reel 只/卷盘 | Reels/Inner Box 卷盘/盒 | Units/Inner Box 只/盒 | Inner Boxes/Outer Box 盒/箱 | Units/Outer Box 只/箱 | Reel | Inner Box 盒 | Outer Box 箱 |
| PDFN5*6 | 5000 | 2 | 10000 | 6 | 60000 | 13”×12 | 360×360×50 | 380×335×366 |

## / Notices